Fast, precision-perfect wafering

High flexibility and precise process control

The automatic wet processing systems for 200 mm and 300 mm wafers support processing with and without carriers. They are engineered for precise process monitoring, high productivity and flexibility during production. RENA wafering systems offer maximum production quality and throughput with the flexibility to be adjusted to customer processes. Fitted with a transport system that allows for an etch-stop in <1 sec., RENA wafering systems stand out from the crowd.

Areas of application

• Acid etching after lapping
• Post polish cleaning
• Final cleaning

Features and benefits

• Precision-perfect process monitoring for tight process control
• Flexible adjustment to specific production specifications
• Full compliance with the SEMI standard
• Processing with and without carriers
• High throughput rates
• Ultra fast etch stop in under one second
• Flexible input and output solutions (FOUP, SMIF, stockers, OHT)
Technical Data Wafering

**Process capabilities**
- Optimized shape control via high uniformity acid etching
- With carrier or carrierless
- Etching, post-polish cleaning and final cleaning
- Cleaning and rinsing with megasonic
- HF-Ozone drying, hot water drying or IPA marangoni drying

**Manufacturing capabilities**
- E-MTBFp > 500h
- Uptime > 96%
- Advanced process control and manufacturing - FDC, R2R Control, EHM, real-time data collection

**Dimensions**

<table>
<thead>
<tr>
<th></th>
<th>Width*</th>
<th>Height including flow box</th>
<th>Length</th>
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<tbody>
<tr>
<td></td>
<td>2200 mm</td>
<td>3500 mm</td>
<td>according to process specification</td>
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<tr>
<td>* for special applications width can be adapted</td>
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**Options**
- Extended loading/unloading buffer station
- Customised process carriers
- Storage tanks for each chemical and process module decouple dosing from external/central supply of chemicals
- Bulk chemical supply systems